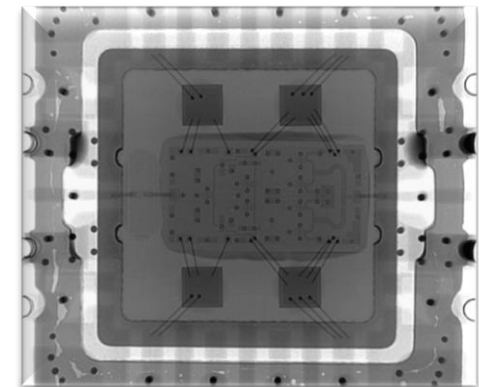
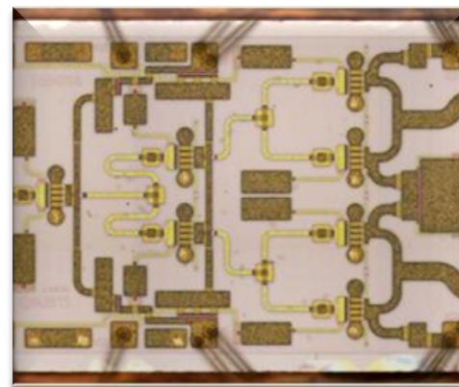


# TGA2594-HM

TriQuint 27 to 31 GHz GaN Power Amplifier

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## Product Analysis Report

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